

Soldered SAM data sheet SAM-λ-A-25.4s

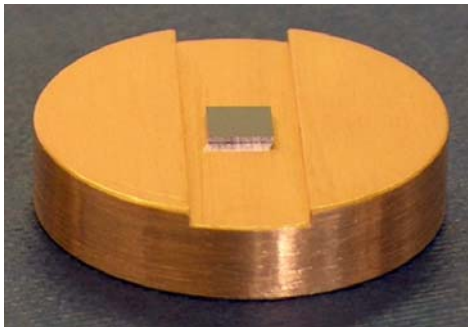
| | | |
|----------------|-----------|-----------------------------|
| GaAs chip area | standard: | 4mm x 4mm |
| | optional: | other dimensions on request |
| Chip thickness | standard: | 400 μm |
| | optional: | 150 μm |

Front side protection the SAM is protected with a dielectric front layer.

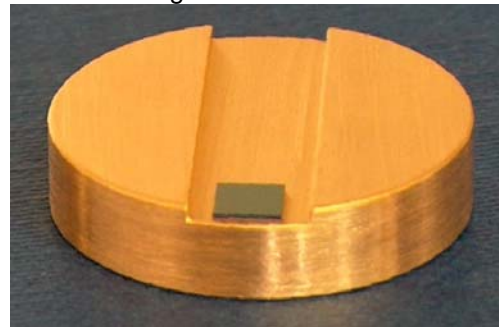
The SAM chip is soldered on a gold plated Cu-cylinder with 25.4 mm Ø using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is at the center of the mount.
- **Optional** the SAM can be soldered on the edge of the mount without extra charges.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, Ø = 25.4 mm
l = 6.0 mm

